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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/792,244	03/03/2004	David R. Hembree	3592.10US (97-0321.10/US)		
24247	90 12/14/2004		EXAMINER		
TRASK BRI	TT	MITCHELL, JAMES M			
P.O. BOX 255	0				
SALT LAKE	CITY, UT 84110		ART UNIT	PAPER NUMBER	
	,		2813		

DATE MAILED: 12/14/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

U.S.	Pa	lent an	id Trade	mark	Offic
PT	OL	-326	(Rev.	1-04	4)

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

Paper No(s)/Mail Date 3/3/04,8/30/04.

3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)

Paper No(s)/Mail Date. ___

6) Other:

5) Notice of Informal Patent Application (PTO-152)

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DETAILED ACTION

This office action is in response to the preliminary amendment field May 17, 2004.

Double Patenting

The nonstatutory double patenting rejection is based on a judicially created doctrine grounded in public policy (a policy reflected in the statute) so as to prevent the unjustified or improper timewise extension of the "right to exclude" granted by a patent and to prevent possible harassment by multiple assignees. See *In re Goodman*, 11 F.3d 1046, 29 USPQ2d 2010 (Fed. Cir. 1993); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985); *In re Van Ornum*, 686 F.2d 937, 214 USPQ 761 (CCPA 1982); *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970);and, *In re Thorington*, 418 F.2d 528, 163 USPQ 644 (CCPA 1969).

A timely filed terminal disclaimer in compliance with 37 CFR 1.321(c) may be used to overcome an actual or provisional rejection based on a nonstatutory double patenting ground provided the conflicting application or patent is shown to be commonly owned with this application. See 37 CFR 1.130(b).

Effective January 1, 1994, a registered attorney or agent of record may sign a terminal disclaimer. A terminal disclaimer signed by the assignee must fully comply with 37 CFR 3.73(b).

Claims 1-10 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 8 and 9 of Hembree (U.S. Patent No. 6,229,204) in view of Chia et al. (U.S. Patent 6,225,695). Hembree does not disclose a glob top material filling any space between the substrate and die. Chia (Fig. 2) utilizes a glob top material ("underfill material"; 212, 312) filling any space between the substrate and die (Fig. It would have been obvious to one of ordinary skill in the art at the time the invention was made to incorporate filling any space between the substrate and die of Hembree in order to protect the solder balls/bumps of Hembree as taught by Chia (Col.2, Lines 32-34).

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Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1, 3, 4, 6, 8 and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mertol (U.S. 5,909,056) in combination with Block et al. (U.S. 5,137,959).

Merol (Fig 3) discloses a semiconductor assembly comprising: a substrate (306) having a plurality of circuits (i.e. in contact with balls) on a portion of a surface thereof; a semiconductor die (311) having a plurality of bond pads located on an active surface thereof (i.e. portion in contact with balls) and having a back side surface; a plurality of solder balls (308) connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate; one of a glob top material (309,310) filling any space between the substrate and the semiconductor die; an thermal interface material (302) contacting at least a portion of the back side surface of the semiconductor die; and a heat sink cap (300) covering the interface, the semiconductor die, the plurality of solder balls, and a portion of the substrate, the heat sink cap contacting at least a portion the interface.

Mertol does not appear to show that the interface is a compliant, adhesive, gel elastomer, cross linked silicone, filled with thermally conductive material.

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Block utilizes an interface that is a compliant, adhesive, gel elastomer, cross linked silicone, filled with thermally conductive material (Col. 1, Lines 55-65).

It would have been obvious to one of ordinary skill at the time the invention was made to form the interface of Mertol with a compliant, adhesive, gel elastomer, cross linked silicone, filled with thermally conductive material in order to improve thermal conductivity as taught by Block (Col. 1, Lines 41-45)

Claims 2, 5, 7, 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mertol (U.S. 5,909,056) and Block et al. (U.S. 5,137,959) as applied to claims 1, 4, 6 and 9 and further in combination with Chia et al. (U.S. 6,225,695).

Neither Mertol nor Block appears to shoe the heat-dissipating member with fins. Chia teaches the use of fins (Fig 1A).

It would have been obvious to one of ordinary skill in the art to incorporate fins on the heat-dissipating member of Mertol in order to order to provide greater surface area for cooling as taught by Chai ((Col. 2, Lines 53-55).

Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Feinberg (U.S. 5,060,114).

The prior art in Feinberg discloses the use of silicone as a thermal interface between an electronic device and heat-dissipating member.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James M. Mitchell whose telephone number is (571) 272-1931. The examiner can normally be reached on M-F 8:00-4:00.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Movember 29, 2004

CARL WHITEHEAD, JR.

SUPERVISORY PAPENT FXAMINER

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